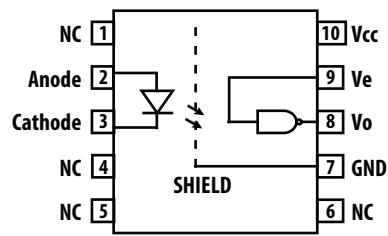


Functional Diagram



NOTE A 0.1- μ F bypass capacitor must be connected between pins V_{CC} and GND.

Truth Table (Positive Logic)

LED	ENABLE	OUTPUT
On	H	L
Off	H	H
On	L	H
Off	L	H
On	NC	L
Off	NC	H

Ordering Information

ACNV2601 is UL recognized with 7500 V_{rms} for 1 minute per UL1577.

Part Number	Option	Package	Surface Mount	Gull Wing	Tape & Reel	UL 7500 V_{rms} /1 Minute Rating	IEC/EN/DIN EN 60747-5-5	Quantity
	RoHS Compliant							
ACNV2601	-000E	500 mil DIP-10				X	X	35 per tube
	-300E		X	X		X	X	35 per tube
	-500E		X	X	X	X	X	500 per reel

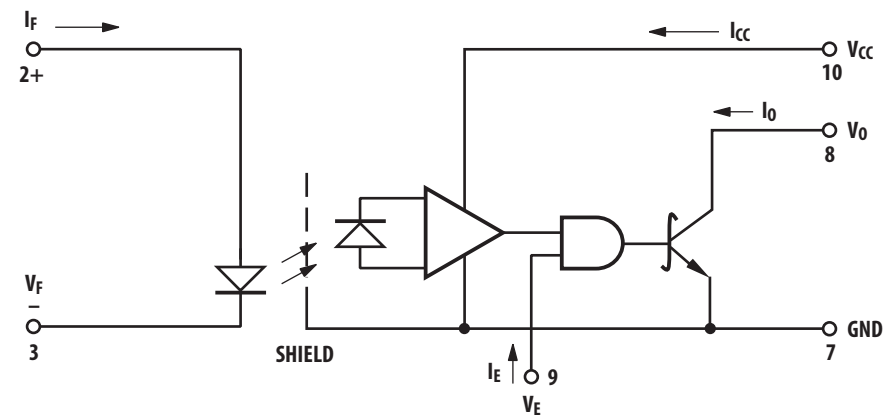
To order, choose a part number from the Part Number column and combine with the desired option from the Option column to form an order entry.

Example 1:

ACNV2601-500E to order product of 500 mil DIP-10 Widebody with Gull Wing Surface Mount package in Tape and Reel packaging with both UL 7500 V_{rms} /1 min and IEC/EN/DIN EN 60747-5-5 Safety Approval in RoHS compliant.

Option data sheets are available. Contact your Broadcom sales representative or authorized distributor for information.

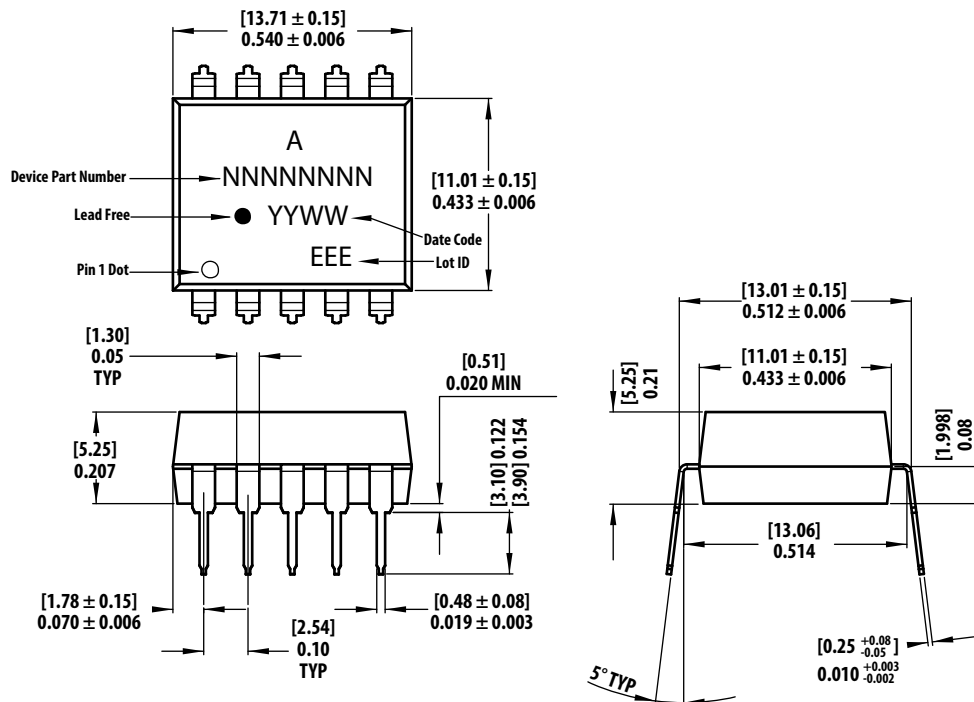
Schematic



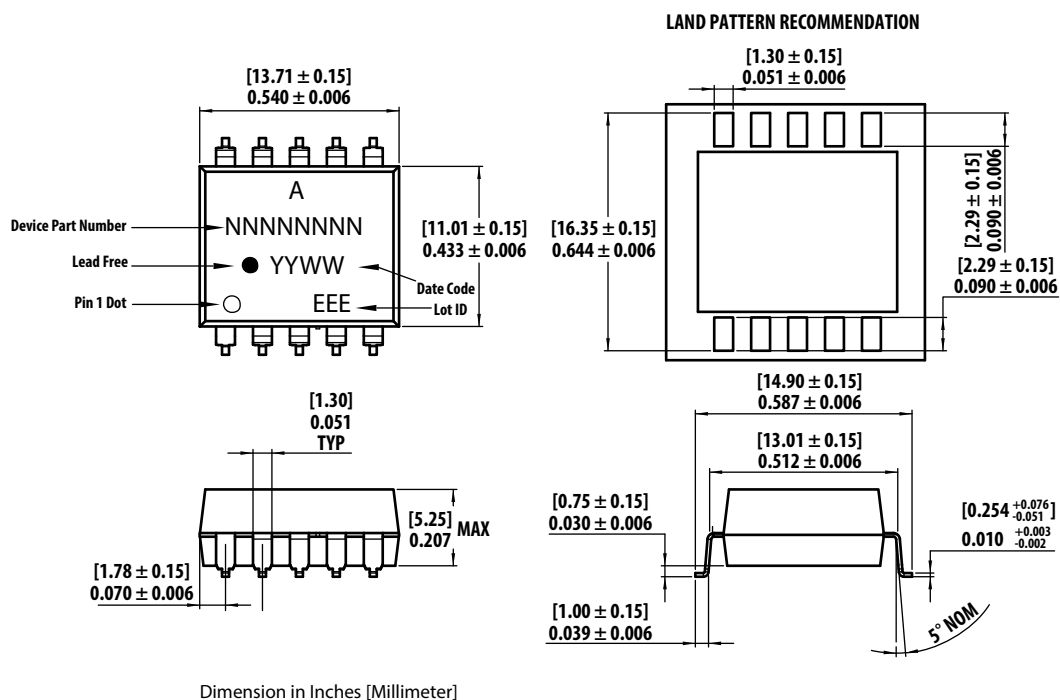
NOTE Use of a 0.1- μ F bypass capacitor connected between pins of 7 and 10 is recommended.

Package Drawings

10-Pin Widebody (500 mils) DIP Package



10-Pin Widebody (500 mils) DIP Package with Gull Wing Surface Mount Option 300



Solder Reflow Profile

Recommended reflow condition as per JEDEC Standard, J-STD-020 (latest revision). Non-Halide Flux should be used.

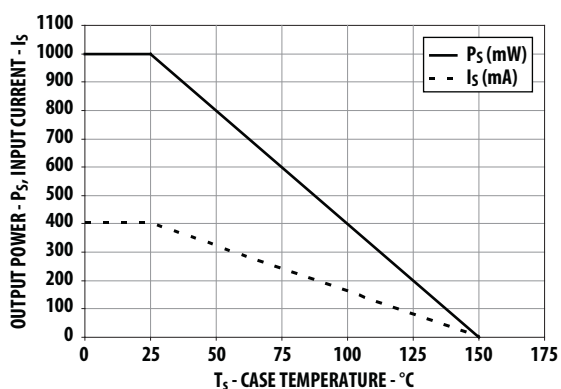
Insulation and Safety Related Specifications

Parameter	Symbol	ACNV2601	Unit	Conditions
Minimum External Air Gap (External Clearance)	L(101)	13	mm	Measured from input terminals to output terminals, shortest distance through air.
Minimum External Tracking (External Creepage)	L(102)	13	mm	Measured from input terminals to output terminals, shortest distance path along body.
Minimum Internal Plastic Gap (Internal Clearance)		2.0	mm	Through insulation distance conductor to conductor, usually the straight line distance thickness between the emitter and detector.
Minimum Internal Tracking (Internal Creepage)		4.6	mm	Measured from input terminals to output terminals, along internal cavity.
Tracking Resistance (Comparative Tracking Index)	CTI	200	V	DIN IEC 112/VDE 0303 Part 1.
Isolation Group		IIIa		Material Group (DIN VDE 0110, 1/89, Table 1).

IEC/EN/DIN EN 60747-5-5 Insulation Characteristics^a

Description	Symbol	Characteristic	Unit
Installation Classification per DIN VDE 0110/1.89, Table 1 For Rated Mains Voltage $\leq 600 V_{rms}$ For Rated Mains Voltage $\leq 1000 V_{rms}$		I – IV I – III	
Climatic Classification		55/105/21	
Pollution Degree (DIN VDE 0110/1.89)		2	
Maximum Working Insulation Voltage	V_{IORM}	2262	V_{peak}
Input to Output Test Voltage, Method b ^a $V_{IORM} \times 1.875 = V_{PR}$, 100% Production Test with $t_m = 1$ sec, Partial Discharge < 5 pC	V_{PR}	4241	V_{peak}
Input to Output Test Voltage, Method a ^a $V_{IORM} \times 1.6 = V_{PR}$, Type and Sample Test, $t_m = 10$ sec, Partial Discharge < 5 pC	V_{PR}	3619	V_{peak}
Highest Allowable Overvoltage (Transient Overvoltage $t_{ini} = 60$ sec)	V_{IOTM}	12000	V_{peak}
Safety-Limiting Values — Maximum Values Allowed in the Event of a Failure			
Case Temperature	T_S	150	$^{\circ}C$
Input Current ^b	$I_{S, INPUT}$	400	mA
Output Power ^b	$P_{S, OUTPUT}$	1	W
Insulation Resistance at T_S , $V_{IO} = 500V$	R_S	$>10^9$	Ω

- a. Refer to the optocoupler section of the Isolation and Control Components Designer's Catalog, under Product Safety Regulations section, (IEC/EN/DIN EN 60747-5-5) for a detailed description of Method a and Method b partial discharge test profiles.
- b. Refer to the following figure for dependence of P_S and I_S on ambient temperature:



NOTE These optocouplers are suitable for safe electrical isolation only within the safety limit data. Maintenance of the safety data shall be ensured by means of protective circuits.

Absolute Maximum Ratings

Parameter	Symbol	Min.	Max.	Unit
Storage Temperature	T_S	-55	125	°C
Operating Temperature	T_A	-40	105	°C
Average Input Current	$I_{F(AVG)}$	—	20	mA
Reverse Input Voltage	V_R	—	3	V
Input Power Dissipation	P_I	—	40	mW
Supply Voltage (1 Minute Maximum)	V_{CC}	—	7	V
Enable Input Voltage (Not to exceed V_{CC} by more than 500 mV)	V_E	—	$V_{CC} + 0.5$	V
Enable Input Current	I_E	—	5	mA
Output Collector Current	I_O	—	50	mA
Output Collector Voltage	V_O	—	7	V
Output Collector Power Dissipation	P_O	—	85	mW
Lead Solder Temperature	T_{LS}	—	245°C for 10 sec, up to seat plane	

Recommended Operating Conditions

Parameter	Symbol	Min.	Max.	Unit	Notes
Input Current, Low Level	I_{FL}^a	0	250	μA	
Input Current, High Level	I_{FH}^b	9	16	mA	^c
Power Supply Voltage	V_{CC}	4.5	5.5	V	
Low Level Enable Voltage	V_{EL}	0	0.8	V	
High Level Enable Voltage	V_{EH}	2.0	V_{CC}	V	
Operating Temperature	T_A	-40	105	°C	
Fan Out (at $R_L = 1\text{ k}\Omega$)	N	—	5	TTL Loads	
Output Pull-up Resistor	R_L	330	4k	Ω	

a. The off condition can also be guaranteed by ensuring that V_{FL} 0.8V.

b. The initial switching threshold is 8 mA or less. It is recommended that 9 mA to 16 mA be used for best performance and to permit at least a 20% LED degradation guardband.

c. Peaking circuits may produce transient input currents up to 50-mA, 50-ns maximum pulse width, provided average current does not exceed 20 mA.

Electrical Specifications (DC)

Over recommended operating conditions unless otherwise specified. All typicals at $V_{CC} = 5V$, $T_A = 25^\circ C$.

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions	Fig.	Notes
High Level Output Current	I_{OH}	—	5.5	100	μA	$V_{CC} = 5.5V$, $V_E = 2.0V$ $V_O = 5.5V$, $I_{FL} = 250 \mu A$		a
Input Threshold Current	I_{TH}	—	3.5	8	mA	$V_{CC} = 5.5V$, $V_E = 2.0V$, $V_O = 0.6V$, $I_{OL} > 13 \text{ mA}$	1, 2	a
Low Level Output Voltage	V_{OL}	—	0.35	0.6	V	$V_{CC} = 5.5V$, $V_E = 2.0V$, $I_F = 8 \text{ mA}$, $I_{OL(Sinking)} = 13 \text{ mA}$	1, 2, 3, 4	a
High Level Supply Current	I_{CCH}	—	7.0	12	mA	$V_E = 0.5V$	$V_{CC} = 5.5V$, $I_F = 0 \text{ mA}$	
		—	6.5	—		$V_E = V_{CC}$		
Low Level Supply Current	I_{CCL}	—	9.0	13	mA	$V_E = 0.5V$	$V_{CC} = 5.5V$, $I_F = 10 \text{ mA}$	
		—	8.5	—		$V_E = V_{CC}$		
High Level Enable Current	I_{EH}	—	−0.7	—	mA	$V_{CC} = 5.5V$, $V_E = 2.0V$		
Low Level Enable Current	I_{EL}	—	−0.9	—	mA	$V_{CC} = 5.5V$, $V_E = 0.5V$		
High Level Enable Voltage	V_{EH}	2.0	—	—	mA	$V_{CC} = 5.5V$, $V_E = 2.0V$		a
Low Level Enable Voltage	V_{EL}	—	—	0.8	mA	$V_{CC} = 5.5V$, $V_E = 0.5V$		
Input Forward Voltage	V_F	1.25	1.64	1.85	V	$T_A = 25^\circ C$	$I_F = 10 \text{ mA}$	5
		1.2	—	2.05				
Input Reverse Breakdown Voltage	BV_R	5	—	—	V	$I_R = 100 \mu A$, $T_A = 25^\circ C$		
Input Capacitance	C_{IN}	—	60	—	pF	$f = 1 \text{ MHz}$, $V_F = 0V$		
Input Diode Temperature Coefficient	$\Delta V_F / \Delta T_A$	—	−1.9	—	mV/ $^\circ C$	$I_F = 10 \text{ mA}$		

a. No external pull-up is required for a high logic state on the enable input. If the V_E pin is not used, tying V_E to V_{CC} results in improved CM_R performance

Switching Specifications (AC)

Over recommended temperature ($T_A = -40^\circ\text{C}$ to $+105^\circ\text{C}$), $V_{CC} = 5\text{V}$, $I_F = 10\text{ mA}$ unless otherwise specified. All typicals are at $T_A = 25^\circ\text{C}$, $V_{CC} = 5\text{V}$.

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions	Fig.	Notes
Propagation Delay Time to High Output Level	t_{PLH}	30	50	80	ns	$T_A = 25^\circ\text{C}$	6, 7, 8	a, b
				120				
Propagation Delay Time to Low Output Level	t_{PHL}	35	55	80	ns	$T_A = 25^\circ\text{C}$		c, b
				120				
Pulse Width Distortion	$ t_{PHL} - t_{PLH} $	—	5	40	ns	$R_L = 350\Omega$, $C_L = 15\text{ pF}$	6, 7, 8, 9	b
Propagation Delay Skew	t_{psk}	—		50	ns			d, b
Output Rise Time (10% to 90%)	T_r	—	25	—	ns		10	b
Output Fall Time (10% to 90%)	T_f	—	10	—	ns		10	b
Propagation Delay Time of Enable from V_{EH} to V_{EL}	t_{ELH}	—	30	—	ns	$R_L = 350\Omega$, $C_L = 15\text{ pF}$, $V_{EL} = 0\text{V}$, $V_{EH} = 3\text{V}$	11, 12	e
Propagation Delay Time of Enable from V_{EL} to V_{EH}	t_{EHL}	—	20	—	ns	$R_L = 350\Omega$, $C_L = 15\text{ pF}$, $V_{EL} = 0\text{V}$, $V_{EH} = 3\text{V}$	11, 12	f
Output High Level Common Mode Transient Immunity	$ CM_H $	20	25	—	kV/ μs	$V_{CC} = 5\text{V}$, $I_F = 0\text{ mA}$, $V_{O(MIN)} = 2\text{V}$, $R_L = 350\Omega$, $T_A = 25^\circ\text{C}$, $V_{CM} = 1500\text{V}$	13	g, h, b
Output Low Level Common Mode Transient Immunity	$ CM_L $	20	25	—	kV/ μs	$V_{CC} = 5\text{V}$, $I_F = 10\text{ mA}$, $V_{O(MAX)} = 0.8\text{V}$, $R_L = 350\Omega$, $T_A = 25^\circ\text{C}$, $V_{CM} = 1500\text{V}$		h, i, b

- The t_{PLH} propagation delay is measured from the 5 mA point on the falling edge of the input pulse to the 1.5V point on the rising edge of the output pulse.
- No external pull-up is required for a high logic state on the enable input. If the V_E pin is not used, tying V_E to V_{CC} results in improved CM_R performance.
- The t_{PHL} propagation delay is measured from the 5 mA point on the rising edge of the input pulse to the 1.5V point on the falling edge of the output pulse.
- t_{psk} is equal to the worst-case difference in t_{PHL} and/or t_{PLH} that is seen between units at any given temperature and specified test conditions.
- The t_{ELH} enable propagation delay is measured from the 1.5V point on the falling edge of the enable input pulse to the 1.5V point on the rising edge of the output pulse.
- The t_{EHL} enable propagation delay is measured from the 1.5V point on the rising edge of the enable input pulse to the 1.5V point on the falling edge of the output pulse.
- CM_H is the maximum tolerable rate of rise of the common mode voltage to ensure that the output remains in a high logic state (i.e., $V_O > 2.0\text{V}$).
- For sinusoidal voltages, $(|dV_{CM}|/dt)_{\max} = \pi f_{CM} V_{CM(p-p)}$.
- CM_L is the maximum tolerable rate of fall of the common mode voltage to ensure that the output remains in a low logic state (i.e., $V_O < 0.8\text{V}$).

Package Characteristics

All typicals are at $T_A = 25^\circ\text{C}$.

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions	Fig.	Notes
Input-Output Insulation	V_{ISO}	7500	—	—	V_{rms}	$RH < 50\%$ for 1 min., $T_A = 25^\circ\text{C}$		a, b
Input-Output Resistance	R_{I-O}	10^{12}	—	—	Ω	$V_{I-O} = 500\text{V}$		a
Input-Output Capacitance	C_{I-O}	—	0.5	0.6	pF	$f = 1\text{ MHz}$, $T_A = 25^\circ\text{C}$		a

- Device considered a two-terminal device: pins 1, 2, 3, 4 and 5 shorted together, and pins 6, 7, 8, 9 and 10 shorted together.
- In accordance with UL1577, each optocoupler is proof tested by applying an insulation test voltage $\geq 9000 V_{rms}$ for one second (leakage detection current limit, $I_{I-O} \leq 5\text{ }\mu\text{A}$). This test is performed before the 100% production test for partial discharge (Method b) shown in the [IEC/EN/DIN EN 60747-5-5 Insulation Characteristics^a](#) table, if applicable.

Figure 1 Typical Output Voltage vs. Forward Input Voltage Current

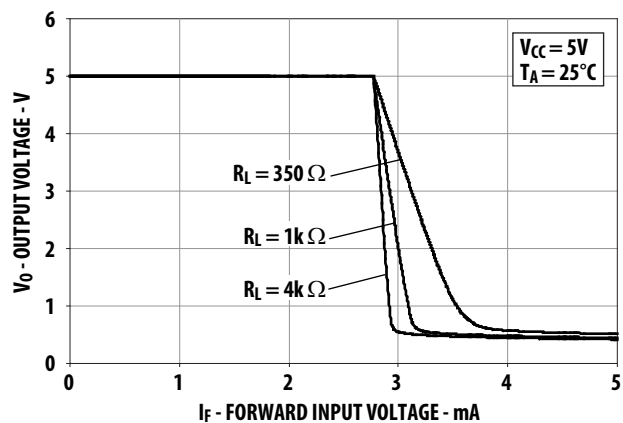


Figure 2 Typical Input Threshold Current vs. Temperature

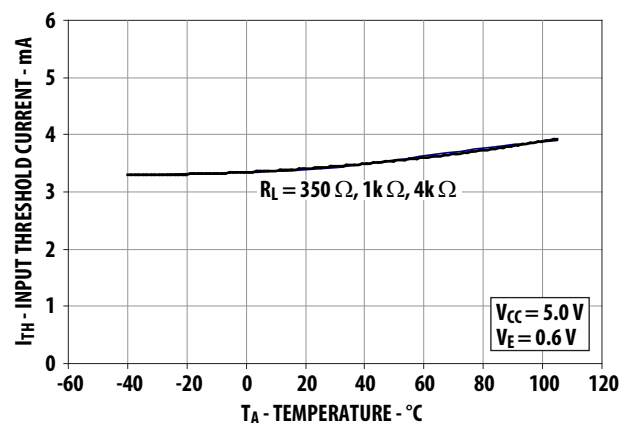


Figure 3 Typical Low Level Output Voltage vs. Temperature

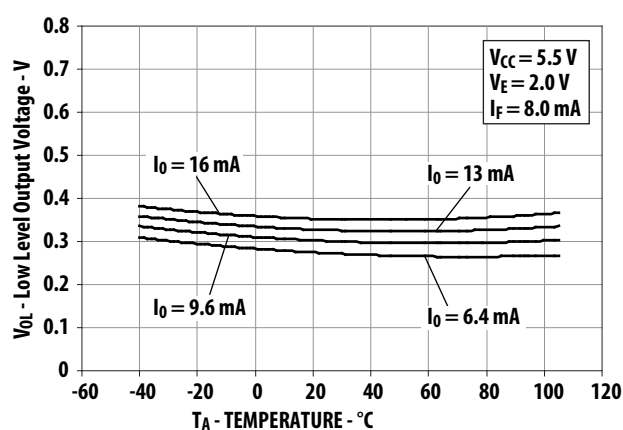


Figure 4 Typical Low Level Output Current vs. Temperature

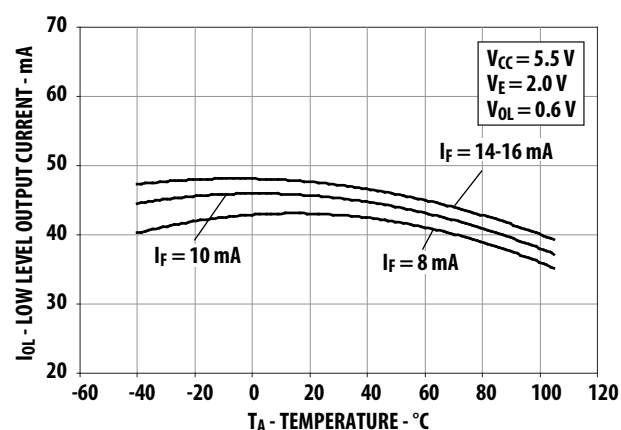


Figure 5 Typical Input Diode Forward Characteristic

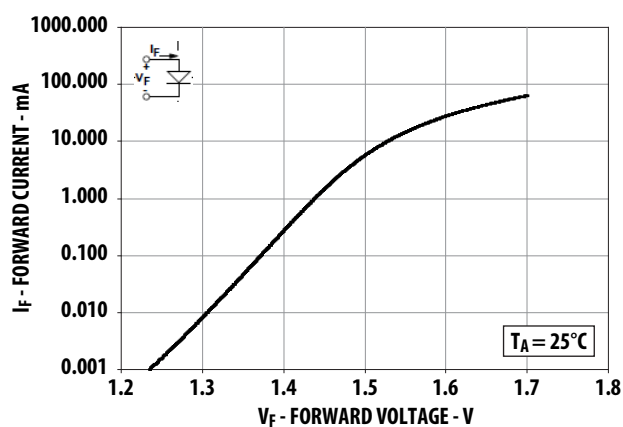


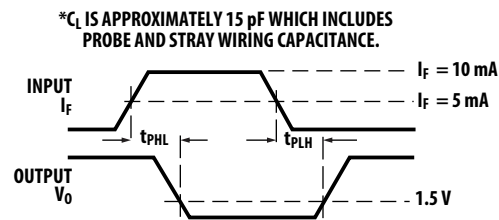
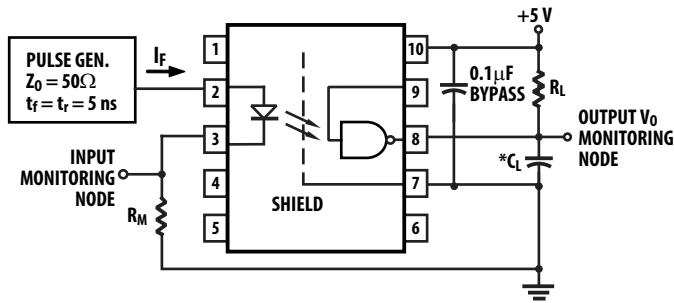
Figure 6 Test Circuit for t_{pHL} and t_{pLH} 

Figure 7 Typical Propagation Delay vs. Temperature

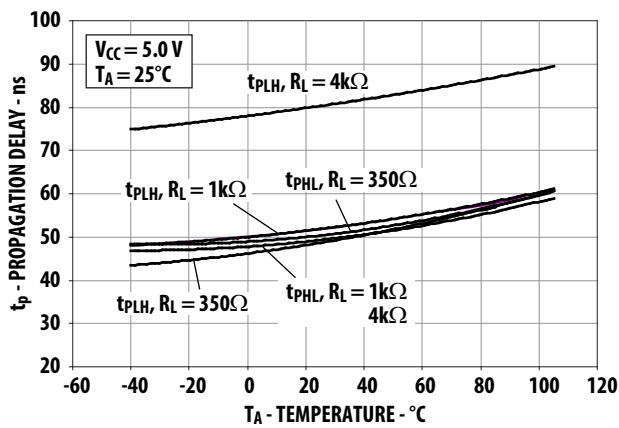


Figure 8 Typical Propagation Delay vs. Pulse Input Current

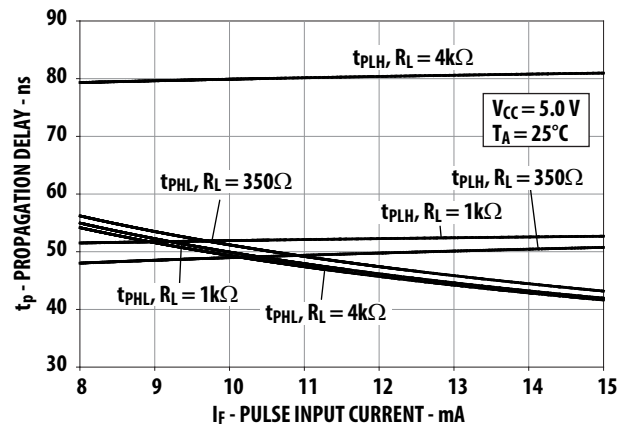


Figure 9 Typical Pulse Width Distortion vs. Temperature

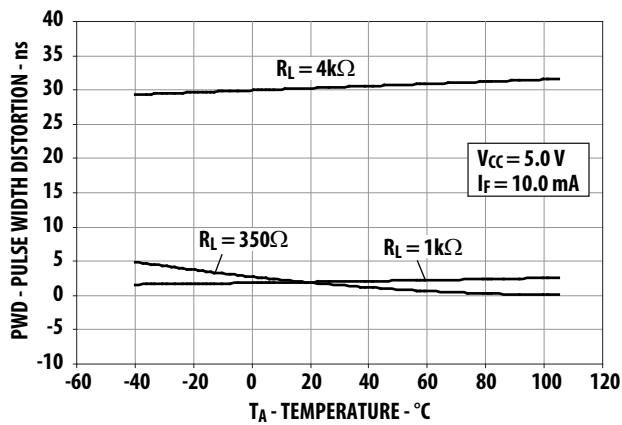


Figure 10 Typical Rise and Fall Time vs. Temperature

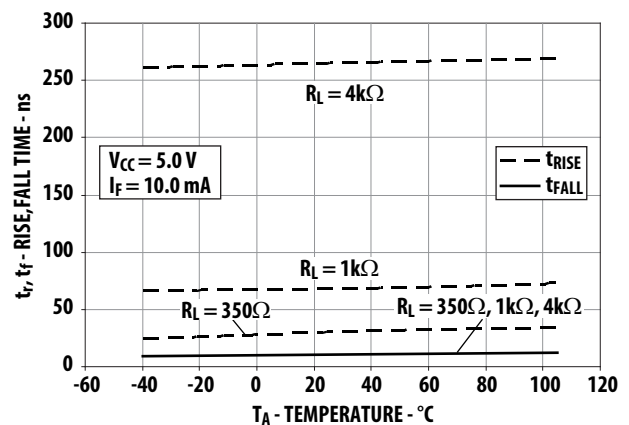


Figure 11 Test Circuit for t_{EHL} and t_{ELH}

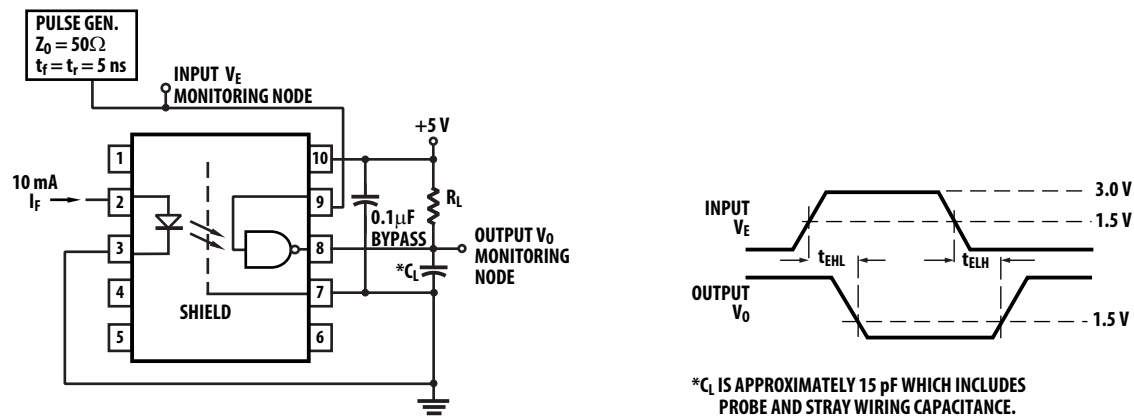


Figure 12 Typical Enable Propagation Delay vs. Temperature

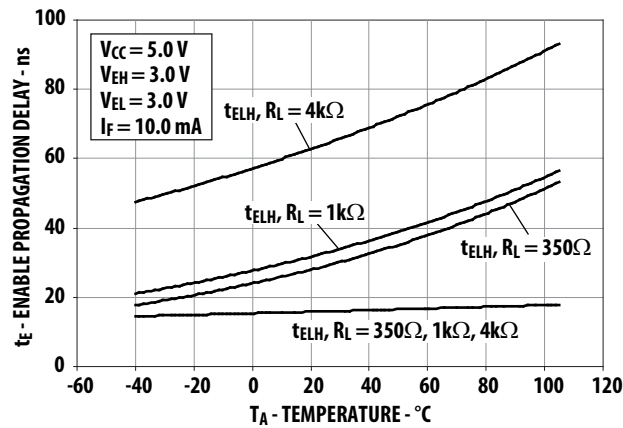


Figure 13 Test Circuit for Common Mode Transient Immunity and Typical Waveforms

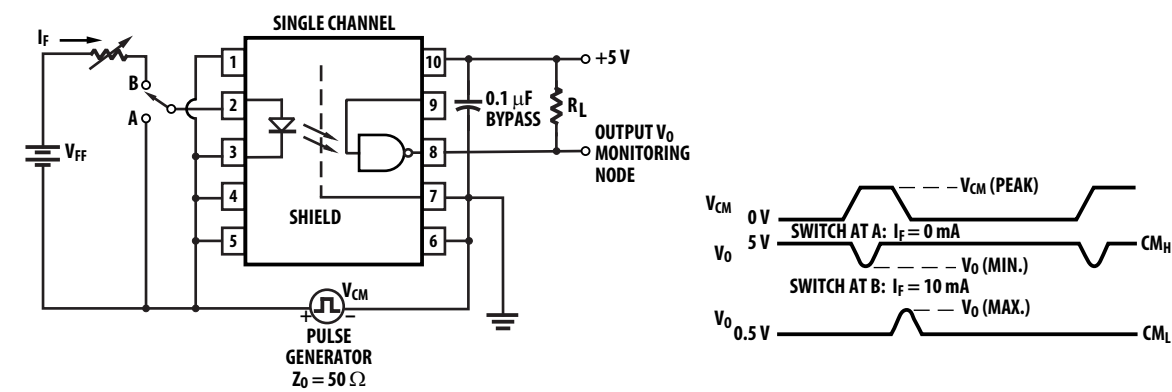
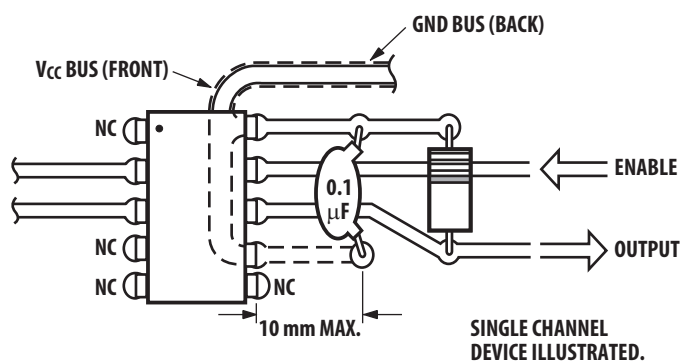


Figure 14 Recommended Printed Circuit Board Layout



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